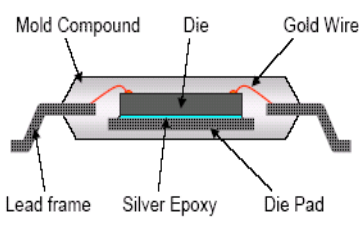


Material Declaration

Compliance Date: Jun./08/2022

RoHS Compliance: Yes

MSL: 3

Pin count /Package		44L TSOPII (400mil)								
Model (Part) Number		AS6CE1016A-45ZIN								
Package Weight (mg)		441.91								
Composed parts	Purpose	Weight (mg)	%	ppm	Material	CAS No.	Weight (mg)	Material wt% of total Mass	Material wt% of Sub part	
Chip	Water Circuit	2.49	0.56	5,635	Silicon	7440-21-3	2.490	0.563%	100.00%	
Bonding Wire	Conductivity	0.43	0.10	973	Gold	7440-57-5	0.430	0.097%	100.00%	
Die Attach	Conductivity	0.19	0.04	430	Silver Power	7440-22-4	0.145	0.033%	76.50%	
					Bisphenol F Type Epoxy Resin	9003-36-5	0.005	0.001%	2.50%	
					Epoxy resin	Trade secret	0.014	0.003%	7.50%	
					Diluent	Trade secret	0.005	0.001%	2.50%	
					Ethylene dimethacrylate	97-90-5	0.014	0.003%	7.50%	
					1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0	0.005	0.001%	2.50%	
					Dicyandiamide	461-58-5	0.001	0.0002%	0.50%	
					1,1-Di(t-butylperoxy)cyclohexane	3006-86-8	0.001	0.0002%	0.50%	
Lead Frame	Base Metal	50.31	11.38	113,847	Copper (Cu)	7440-50-8	46.939	10.622%	93.30%	
					Nickel (Ni)	7440-02-0	1.610	0.364%	3.20%	
					Silicon (Si)	7440-21-3	0.365	0.083%	0.73%	
					Magnesium (Mg)	7439-95-4	0.088	0.020%	0.18%	
					Silver (Ag)	7440-22-4	1.308	0.296%	2.60%	
Molding Compound	Chip Protection	383.44	86.77	867,688	Silica(Amorphous) A	60676-86-0	314.421	71.150%	82.00%	
					Silica(Amorphous) B	7631-86-9	25.690	5.814%	6.70%	
					Epoxy Resin A	Trade secret	7.669	1.735%	2.00%	
					Epoxy Resin B	Trade secret	7.669	1.735%	2.00%	
					Phenol Resin	Trade secret	25.690	5.814%	6.70%	
					Carbon Black	1333-86-4	2.301	0.521%	0.60%	
Plating of lead frame	Solder Plating	5.05	1.14	11,428	Tin (Sn)	7440-31-5	5.050	1.143%	100.00%	